

10. The method of manufacturing a semiconductor device of claim 9, further comprising the steps of forming a through hole in said resin layer and filling said through hole with solder. *further comprising*

11. The method of manufacturing a semiconductor device of claim 10, further comprising the step of mounting a solder ball on said solder.

12. The method of manufacturing a semiconductor device of claim 9, further comprising the step of cutting the other one of said resin layer and said semiconductor wafer along said dividing line so as to form a plurality of semiconductor structures.

B' part
13. The method of manufacturing a semiconductor device of claim 9, wherein the step of cutting comprises cutting said resin layer along the dividing line.

14. The method of manufacturing a semiconductor device of claim 9, wherein the step of cutting comprises cutting said semiconductor wafer along the dividing line.

NP1 N
Another plurality of wafers
15. The method of manufacturing a semiconductor device of claim 9, wherein the step of cutting comprises the step of forming a groove in said semiconductor wafer on one side thereof before the step of forming a resin layer.

N
16. The method of manufacturing a semiconductor device of claim 15, wherein the step of forming a resin layer includes filling said groove with a portion of said resin layer.

17. The method of manufacturing a semiconductor device of claim 16, wherein the step of cutting further comprises grinding said semiconductor wafer on a side opposing said one side so as to reach said groove.

18. The method of manufacturing a semiconductor device of claim 15, wherein the step of cutting further comprises grinding said semiconductor wafer on a side opposing said one side so as to reach said groove.

19. The method of manufacturing a semiconductor device of claim 18, further comprising the steps of forming a through hole in said resin layer and filling said through hole with solder.

B' cont.
20. The method of manufacturing a semiconductor device of claim 19, further comprising the step of mounting a solder ball on said solder.

21. The method of manufacturing a semiconductor device of claim 18, further comprising the step of cutting the other one of said resin layer and said semiconductor wafer along said dividing line so as to form a plurality of semiconductor structures.

22. The method of manufacturing a semiconductor device of claim 11, further comprising the step of cutting the other one of said resin layer and said semiconductor wafer along said dividing line so as to form a plurality of semiconductor structures.